

IN THE SPECIFICATION

Please amend the paragraph on page 11, line 17, as follows:

Figure **6D** illustrates a subsequent processing stage where a top metal layer **612** is deposited above the inter-metal dielectric layer **610** in electrical communication with the interconnect vias **606**. Note, for example, operation **508** of the method **500** of Figure 5. Such top metal layer **612** thus serves as the bond pad.